PBSS9110S,126 Datasheet

https://www.DiGi-Electronics.com

DiGi Electronics Part Number	PBSS9110S,126-DG
Manufacturer	NXP USA Inc.
Manufacturer Product Number	PBSS9110S,126
Description	TRANS PNP 100V 1A TO92-3
Detailed Description	Bipolar (BJT) Transistor PNP 100 V 1 A 100MHz 830 mW Through Hole TO-92-3

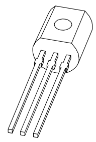
Tel: +00 852-30501935
RFQ Email: Info@DiGi-Electronics.com

Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
PBSS9110S,126	NXP USA Inc.
Series:	Product Status:
-	Obsolete
Transistor Type:	Current - Collector (Ic) (Max):
PNP	1 A
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ Ib, Ic:
100 V	320mV @ 100mA, 1A
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ Ic, Vce:
100nA	150 @ 500mA, 5V
Power - Max:	Frequency - Transition:
830 mW	100MHz
Operating Temperature:	Mounting Type:
150°C (TJ)	Through Hole
Package / Case:	Supplier Device Package:
TO-226-3, TO-92-3 (TO-226AA) Formed Leads	TO-92-3
Base Product Number:	
PBSS9	

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.21.0075	



PBSS9110S

100 V, 1 A PNP low V_{CEsat} (BISS) transistor

Rev. 03 — 22 November 2009 Product data sheet

1. Product profile

1.1 General description

PNP low V_{CEsat} transistor in a SOT54 (SC-43/TO-92) plastic package.

1.2 Features

- SOT54 package
- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability I_C and I_{CM}
- High efficiency leading to less heat generation

1.3 Applications

- Major application segments:
  - Automotive 42 V power
  - Telecom infrastructure
  - Industrial
- Peripheral driver:
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors)
- DC-to-DC converter

1.4 Quick reference data

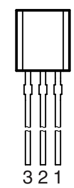
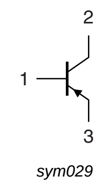
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage		-	-	–100	V
I_C	collector current (DC)		-	-	–1	A
I_{CM}	peak collector current		-	-	–3	A
R_{CEsat}	equivalent on-resistance		-	-	320	mΩ

founded by Philips

2. Pinning information

Table 2. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	base		
2	collector		
3	emitter		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS9110S	-	plastic single-ended leaded (through hole) package; 3 leads	SOT54

4. Marking

Table 4. Marking

Type number	Marking code
PBSS9110S	S9110S[1]

[1] Made in China

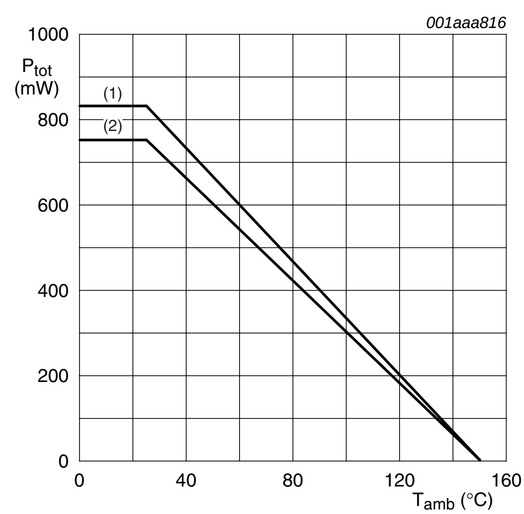
5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	–120	V
V_{CEO}	collector-emitter voltage	open base	-	–100	V
V_{EBO}	emitter-base voltage	open collector	-	–5	V
I_{CM}	peak collector current	$T_{j(max)}$	-	–3	A
I_C	collector current (DC)		-	–1	A
I_B	base current (DC)		-	–0.3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C [1]	-	830	mW
T_j	junction temperature		-	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C
T_{stg}	storage temperature		–65	+150	°C

[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated, standard footprint.



(1) 1cm^2 collector mounting pad

(2) Standard footprint

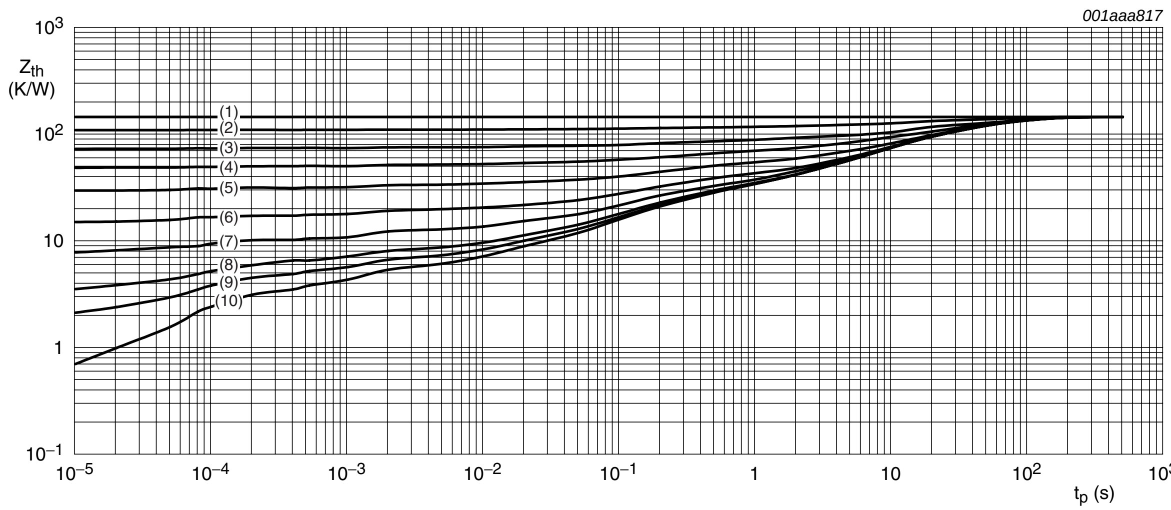
Fig 1. Power derating curves

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	150	K/W

[1] Device mounted on a FR4 printed-circuit board, single-sided copper, tin-plated, standard footprint.



Mounted on FR4 PCB; standard footprint

(1) $\delta = 1$

(2) $\delta = 0.75$

(3) $\delta = 0.5$

(4) $\delta = 0.33$

(5) $\delta = 0.2$

(6) $\delta = 0.1$

(7) $\delta = 0.05$

(8) $\delta = 0.02$

(9) $\delta = 0.01$

(10) $\delta = 0$

Fig 2. Transient thermal impedance as a function of pulse time; typical values

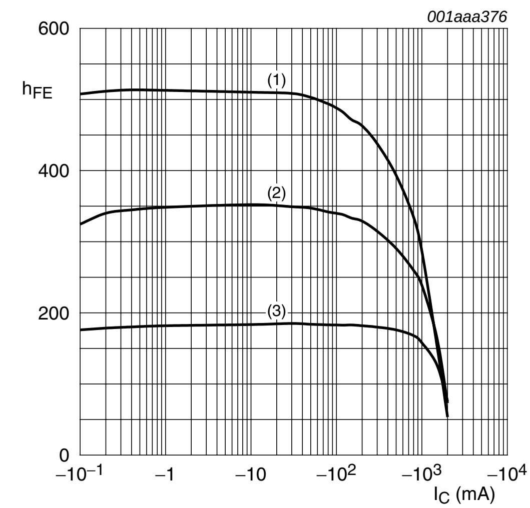
7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = –80 V; I_E = 0 A		-	-	–100	nA
		V_{CB} = –80 V; I_E = 0 A; T_j = 150 °C		-	-	–50	μA
I_{CES}	collector-emitter cut-off current	V_{CE} = –80 V; V_{BE} = 0 V		-	-	–100	nA
I_{EBO}	emitter-base cut-off current	V_{EB} = –4 V; I_C = 0 A		-	-	–100	nA
h_{FE}	DC current gain	V_{CE} = –5 V; I_C = –1 mA		150	-	-	
		V_{CE} = –5 V; I_C = –250 mA		150	-	-	
		V_{CE} = –5 V; I_C = –0.5 A	[1]	150	-	450	
		V_{CE} = –5 V; I_C = –1 A	[1]	125	-	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = –250 mA; I_B = –25 mA		-	-	–120	mV
		I_C = –500 mA; I_B = –50 mA		-	-	–180	mV
		I_C = –1 A; I_B = –100 mA		-	-	–320	mV
R_{CEsat}	equivalent on-resistance	I_C = –1 A; I_B = –100 mA	[1]	-	170	320	mΩ
V_{BEsat}	base-emitter saturation voltage	I_C = –1 A; I_B = –100 mA		-	-	–1.1	V
V_{BEon}	base-emitter turn-on voltage	I_C = –1 A; V_{CE} = –5 V		-	-	–1.0	V
f_T	transition frequency	I_C = –50 mA; V_{CE} = –10 V; f = 100 MHz		100	-	-	MHz
C_c	collector capacitance	I_E = I_e = 0 A; V_{CB} = –10 V; f = 1 MHz		-	-	17	pF

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.



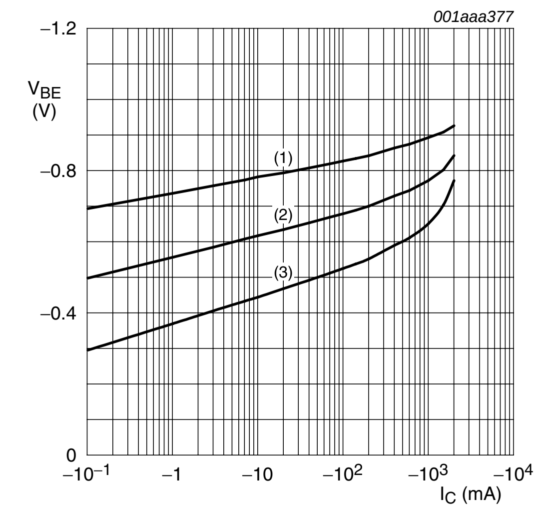
$V_{CE} = -10$ V

(1) $T_{amb} = 100$ °C

(2) $T_{amb} = 25$ °C

(3) $T_{amb} = -55$ °C

Fig 3. DC current gain as a function of collector current; typical values



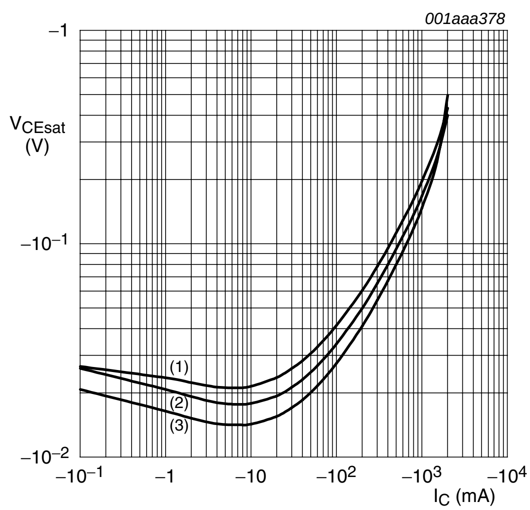
$V_{CE} = -10$ V

(1) $T_{amb} = -55$ °C

(2) $T_{amb} = 25$ °C

(3) $T_{amb} = 100$ °C

Fig 4. Base-emitter voltage as a function of collector current; typical values



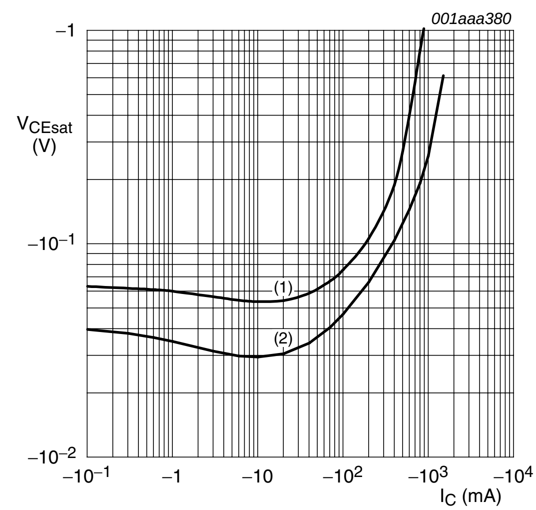
$I_C/I_B = 10$

(1) $T_{amb} = 100$ °C

(2) $T_{amb} = 25$ °C

(3) $T_{amb} = -55$ °C

Fig 5. Collector-emitter saturation voltage as a function of collector current; typical values

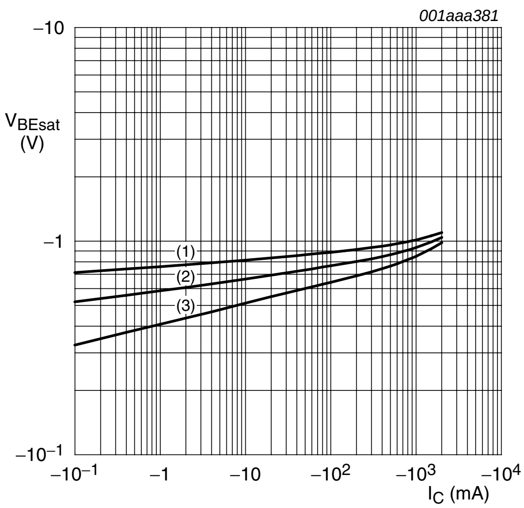


$T_{amb} = 25$ °C

(1) $I_C/I_B = 50$

(2) $I_C/I_B = 20$

Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values



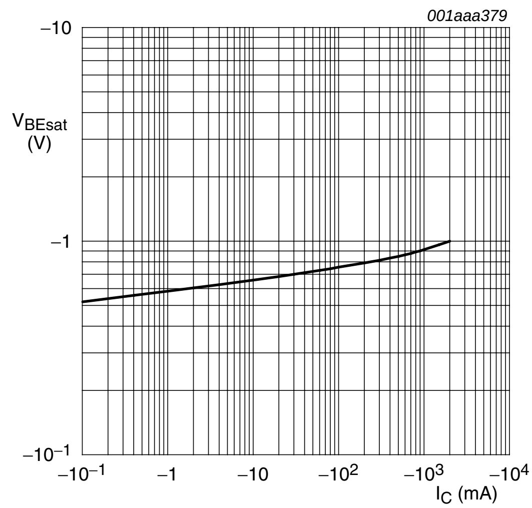
$I_C/I_B = 10$

(1) $T_{amb} = -55$ °C

(2) $T_{amb} = 25$ °C

(3) $T_{amb} = 100$ °C

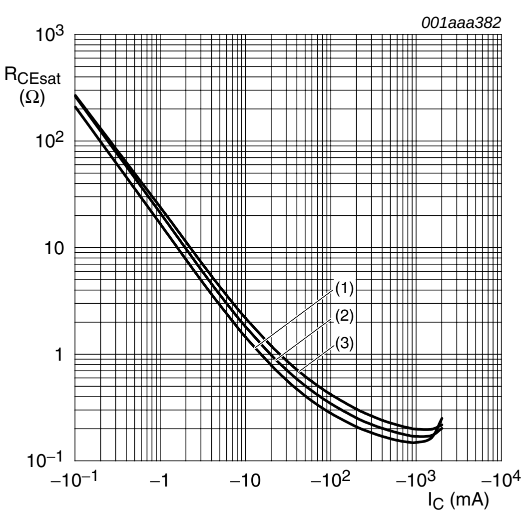
Fig 7. Base-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 20$

$T_{amb} = 25$ °C

Fig 8. Base-emitter saturation voltage as a function of collector current; typical values



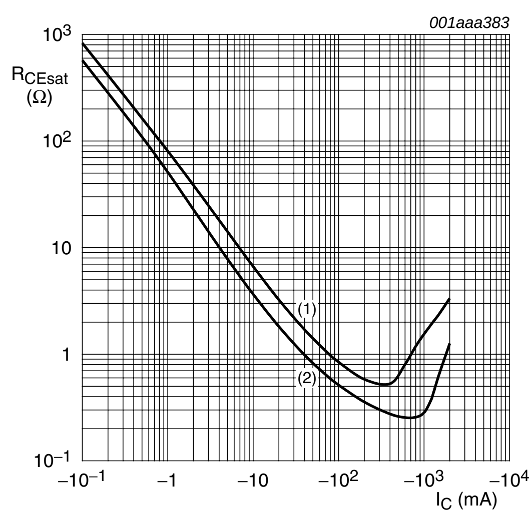
$I_C/I_B = 10$

(1) $T_{amb} = -55$ °C

(2) $T_{amb} = 25$ °C

(3) $T_{amb} = 100$ °C

Fig 9. Equivalent on-resistance as a function of collector current; typical values



$T_{amb} = 25$ °C

(1) $I_C/I_B = 50$

(2) $I_C/I_B = 20$

Fig 10. Equivalent on-resistance as a function of collector current; typical values

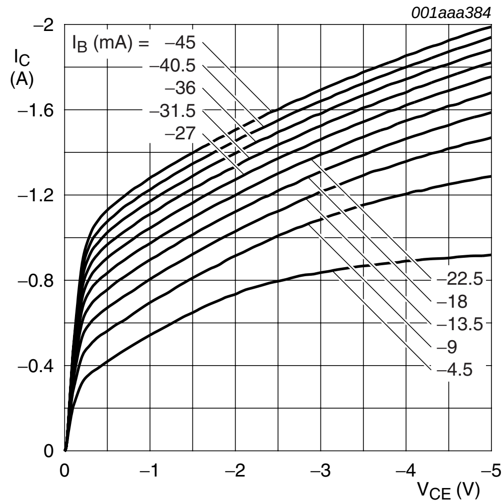
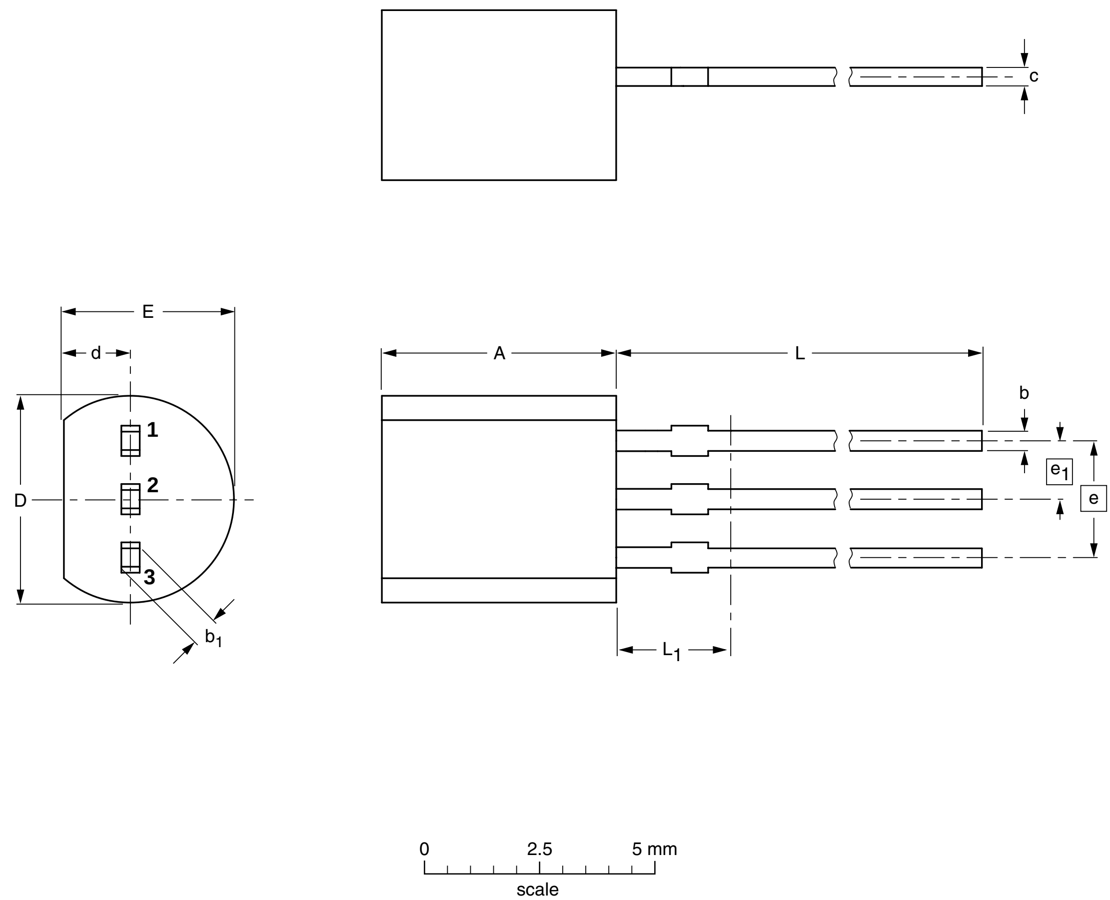


Fig 11. Collector current as a function of collector-emitter voltage; typical values

8. Package outline

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	$L_1^{(1)}$ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~04-06-28~~ 04-11-16

Fig 12. Package outline

9. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS9110S_3	20091122	Product data sheet	-	PBSS9110S_2
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Table 2 "Discrete pinning": amended • Figure 9 "Equivalent on-resistance as a function of collector current; typical values": updated • Figure 10 "Equivalent on-resistance as a function of collector current; typical values": updated • Figure 11 "Collector current as a function of collector-emitter voltage; typical values": updated • Figure 12 "Package outline": updated			
PBSS9110S_2	20040810	Product data	-	PBSS9110S_1
PBSS9110S_1	20040607	Product data	-	-

10. Legal information

10.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

10.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

10.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

10.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

11. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

12. Contents

Date of release: 22 November 2009
Document identifier: PBSS9110S_3

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com

Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.